

IN THE CLAIMS:

Please cancel claims 2, 10 and 17-20 without prejudice to or disclaimer of the subject matter recited therein.

Please amend claims 1 and 9 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Currently Amended) A method for making a package substrate comprising the steps of:

providing a substrate having a top surface and a bottom surface;

forming at least a through slot passing through the top surface and the bottom surface of the substrate so as to form a plurality of side walls inside the through slot and a die-cavity portion;

forming a metal layer on the top surface of the substrate and the side walls inside the through slot;

forming a anti-etching layer on the top surface and the bottom surface of the substrate and the die-cavity portion ~~for hermetically sealing the through slot;~~ slot, the anti-etching layer being a photosensitive dry film;

patterning the anti-etching layer;

etching the metal layer on the top surface of the substrate to form a circuit pattern under the anti-etching layer, the anti-etching layer preventing the metal layer on the side walls of the through slot from etched;

removing the anti-etching layer; and

removing the die-cavity portion of the substrate to form a die-cavity of the substrate having the metal layer on the side walls.

Claim 2. (Canceled)

Claim 3. (Original) The method in accordance with claim 1, wherein the through slot has a width between 0.1mm and 4.0 mm.

Claim 4. (Original) The method in accordance with claim 1, wherein the metal layer on the side walls is in discontinuous configuration after the step of removing the die-cavity portion.

Claim 5. (Original) The method in accordance with claim 1, wherein the through slot is a linear slot.

Claim 6. (Original) The method in accordance with claim 1, wherein the through slot is a L-shaped slot.

Claim 7. (Original) The method in accordance with claim 1, further comprising a step of forming an insulation cover layer on the circuit pattern layer.

Claim 8. (Original) The method in accordance with claim 1, further comprising a step of forming a surface treating layer on the metal layer.

Claim 9. (Currently Amended) A method for making a package substrate comprising the steps of:

providing a substrate having a top surface and a bottom surface, the top surface including a die-cavity region;

forming at least a slot around the die-cavity region so as to form a plurality of side walls inside the slot and a die-cavity portion within the die-cavity region, wherein the die-cavity portion is integrally connected with the substrate;

forming a metal layer on the top surface of the substrate and the side walls;

forming an anti-etching layer on the top surface and the bottom surface of the substrate and the die-cavity portion for hermetically sealing the slot; slot, the anti-etching layer being a photosensitive dry film;

patterning the anti-etching layer;

etching the metal layer on the top surface of the substrate, the anti-etching layer preventing the metal layer on the side walls of the through slot from be etched;

removing the anti-etching layer; and

removing the die-cavity portion of the substrate to form a die-cavity of the substrate having the metal layer on the side walls.

Claim 10. (Canceled)

Claim 11. (Original) The method in accordance with claim 9, wherein the slot has a width between 0.1mm and 4.0 mm.

Claim 12. (Original) The method in accordance with claim 9, wherein the metal layer on the side walls is in discontinuous configuration after the step of removing the die-cavity portion.

Claim 13. (Original) The method in accordance with claim 9, wherein the slot is a linear slot.

Claim 14. (Original) The method in accordance with claim 9, wherein the through slot is a L-shaped slot.

Claim 15. (Original) The method in accordance with claim 9, further comprising a step of forming an insulation cover layer on the circuit pattern layer.

Claim 16. (Original) The method in accordance with claim 9, further comprising a step of forming a surface treating layer on the metal layer.

Claims 17-20. (Canceled)